



PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hui et al.

Serial No.: 09/916,197

Filed: July 27, 2001

For: METHOD FOR ENCAPSULATING
INTERMEDIATE CONDUCTIVE
ELEMENTS CONNECTING A
SEMICONDUCTOR DIE TO A
SUBSTRATE AND SEMICONDUCTOR
DEVICES SO PACKAGED

Confirmation No.: 7070

Examiner: J. Vigushin

Group Art Unit: 2827

Attorney Docket No.: 2269-4712US
(99-1054.00/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

4/25/03

Date

Signature

Deidra Pfeil
Name (Type/Print)

LETTER TO THE CHIEF DRAFTSMAN

Box Issue Fee
Commissioner for Patents
Washington, D.C. 20231

Sir:

Applicants submit herewith revised FIG. 5 which correct errors in the drawings. Specifically, FIG. 5 has been revised to add the reference numeral 42 with appropriate lead line. Attached is a copy of the drawings with the proposed changes marked in red.

No new matter has been added. Approval of the proposed revisions is respectfully requested.

Respectfully submitted,



Brick G. Power
Registration No. 38,581
Attorney for Applicants
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: April 25, 2003

BGP/dlm:djp

Enclosures: Drawings with changes marked in red

Document in ProLaw